


<div> Telink</div>			Telink Semiconductor (Shanghai) CO., LTD Phone: +8621 2028 1118 Fax: 8621 5038 8081 1500 Zuchongzhi Road Bldg 3 PuDong District, Shanghai, China 201203						
Composition Table									
To:		TELINK SEMICONDUCTOR (SHANGHAI) CO., LTD.							
From:		HuaTian Technology (Xi An) Co.,Ltd							
Product Name:		TLSR8355F512ET48							
Weight(Unit):		129.4000 mg						Date:	2023/10/17
	Material name	Vendor	Weight(mg)	Substance Name	CAS No	Weight(mg)	Content (%) Substance	Content (%) Whole chip	Content (ppm)
Die1	Telink Die	SMIC BJ	5.8740	Silicon	7440-21-3	5.8740	100.00%	4.54%	1000000
Die2	GD Die	SMIC BJ	0.2760	Silicon	7440-21-3	0.2760	100.00%	0.21%	1000000
Lead Frame	A194FH	康强	40.4300	Cu	7440-50-8	39.0150	96.50%	31.24%	965000
				Fe	7439-89-6	0.9299	2.30%	0.72%	23000
				P	7723-14-0	0.0606	0.15%	0.05%	1500
				Zn	7440-66-6	0.0809	0.20%	0.06%	2000
				Pb	7439-92-1	0.0020	0.01%	0.00%	50
				Ag	7440-22-4	0.3416	0.85%	0.26%	8450
				DAF	ATB-120U	Henkel	3.0400	Modified Epoxy Resin Phenol, polymer with 3a,4,7,7a-tetrahydro-4,7-methano-1H-indene, glycidyl ether	Proprietary
Reaction product: bisphenol-F-(epichlorhydrin); epoxy resin (number average molecular weight ≤ 700) (old)	119345-05-0	0.6992	23.0%					0.54%	230000
	9003-36-5	0.1520	5.0%					0.12%	50000
Aromatic polyamine	Proprietary	0.1520	5.0%					0.12%	50000
Epoxy Resin	Proprietary	0.0304	1.0%					0.02%	10000
Epoxy	L1-403NCA	LEGEND	3.0000	Diethylene glycol monoethyl ether acetate	112-15-2	0.3000	10.00%	2.32%	100000
				Silica	15468-32-3	1.8000	60.00%	1.39%	600000
				Acylate resin	Proprietary	0.4500	15.00%	0.35%	150000
				Epoxy resin	Proprietary	0.4200	14.00%	0.32%	140000
				Peroxide	Proprietary	0.0300	1.00%	0.02%	10000
				Wire	HS-ES5	乐金	6.0600	Silver:Wire	7440-22-4
Gold	7440-57-5	0.0303	0.5000%					0.02%	5000
Palladium	7440-05-3	0.2727	4.5000%					0.21%	45000
Platinum	7440-6-4	0.0006	0.0100%					0.00%	100
Mold Compound	CEL-9220HF	RESONAC Materials	64.7000						
				Epoxy Resin 1	Trade secret	0.3235	0.50%	0.25%	5000
				Epoxy Resin 2	Trade secret	0.3235	0.50%	0.25%	5000
				Epoxy Resin 3	Trade secret	0.3235	0.50%	0.25%	5000
				Hardener	Trade secret	1.2940	2.00%	1.00%	20000
				Catalyst	Trade secret	0.0065	0.01%	0.01%	100
				Carbon black	1333-86-4	0.1294	0.20%	0.10%	2000
				Amorphous silica1	60676-86-0	57.4471	88.79%	44.40%	887900
				Amorphous silica2	7631-86-9	4.8525	7.50%	3.75%	75000
				Plating	TIN	AISEN	6.0200	Tin	7440-31-5
Others	Trade Secret	0.0006	0.01%					0.00%	100
Total			129.4000			129.4000	100%	1000000	